



Title of Document: REPORT		Issue No. G21-07473	Rev. 0
Customer: All Life Technology		Issue date: November 4, 2021	
Title subject: PIN Plating structure report		Revision date: —	

This is to report on the subject as per your request.

1. Part Number

S4B-EH(LF)(SN)

2. Investigation Result

Please see Appendix.

- PIN Plating structure report

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零件供應商PIN腳電鍍結構調查書

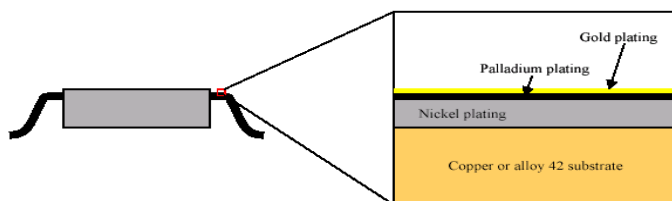
PIN Plating structure report

供應商名稱： J.S.T. MFG CO., LTD.
Company Name
日期： 4-Nov-2021
Date

			依電鍍層由內向外 A > B > C... 格式為(金屬：厚度 um) Lead free Plating from inside to outside A > B > C ... Format (Metal : Thickness um)				
項目 Item	供應商料號 Vendor Part Number	規格內容 Description	鍍層結構A Structure A	鍍層結構B Structure B	鍍層結構C Structure C	鍍層結構D Structure D	鍍層結構E Structure E
1	S4B-EH(LF)(SN)	Connector (Post)	Brass	Cu 0.5um min	Sn 1.0um min	—	—

Sn 材質為： ☐ Matter tin ☐ Bright tin ☒ Other(Reflow)

範例：
Example：



			依電鍍層由內向外 A > B > C... 格式為(金屬：厚度 um) Lead free Plating from inside to outside A > B > C ... Format (Metal : Thickness um)				
項目 Item	供應商料號 Vendor Part Number	規格內容 Description	鍍層結構A Structure A	鍍層結構B Structure B	鍍層結構C Structure C	鍍層結構D Structure D	鍍層結構E Structure E
1	SPN8061	IC	Cu (Basic electrode)	Ni 5um	Pd 1um	Au 1um	

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Writer's signature